Thermal Pad
CPVP-30-F Series

NEW

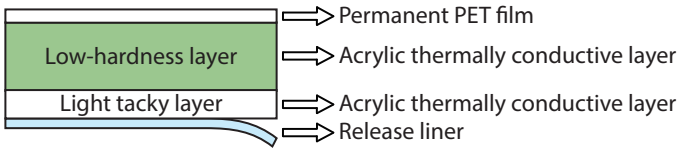
Silicone-Free

Silicone-free, low-hardness, high-thermally conductive pad (3W/m•K)

RoHS Compliant

- The two-layer structured putty can be handled in the same way as a pad
- Has a thermal conductivity of 3.0W/m • K, which is 2.1 times higher than the existing product
- Silicone-free THERMAL PAD contains no siloxane
- With excellent flexibility and stress relaxation, the assembled pad can lower the load on heating elements and PCBs
- Recommended operating temperature: -40 ~125°C
- Bleeds less oil compared with the silicone type

Cross-section view



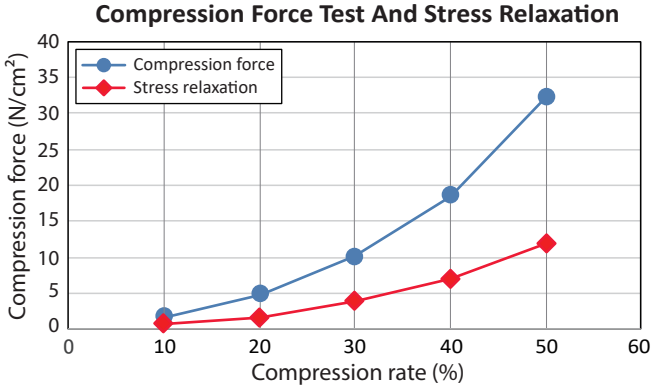
Properties

**Under development*

Part Number	CPVP-30-F
Thickness (mm)	*1.0*, 1.5*, 2.0**, 3.0, 4.0
Thermal Conductivity (W/m•K) *ISO22007-2 Hot-disc method	3.0 (Low-hardness layer)
Hardness (ASKER C) *JIS K 7312	7 (Low-hardness layer)
Hardness (Shore OO) *ASTM D 2240	18 (Low-hardness layer)
Volume Resistivity (Ω • cm) *JIS K 6911	1.0 x 10^{11}
Flame Resistance *UL94	Equivalent to V-0
Color	Green / White
Operating Temperature (°C)	-40 ~ 125

*TEST METHOD

Compression Force Test And Stress Relaxation



Test Conditions:
Sample Dimensions: □10mm (t=4.0mm)
Cross-head speed: 1mm/min
Compression plate material:
Upper: Stainless steel ϕ28mm
Lower: Gold plated copper ϕ106mm
***Compressive force is the largest load value immediately after compression**

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Please request for detailed product specification data prior to purchase